

M-Cloud[®]

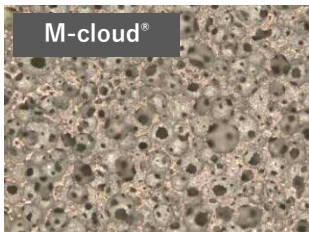
Super-Porous metal bond Wheel



M-Cloud[®] Features

- ❖ Advantages of both Vitrified and metal bond wheels (Free Cutting plus Wear Resistance)
- ❖ Reduce Cycle Time
- ❖ Reduce burden of post process by finer grain selection
- ❖ Stable Wafer quality by outstanding discharge of sludge and cooling effect.

Unique Porous Structure



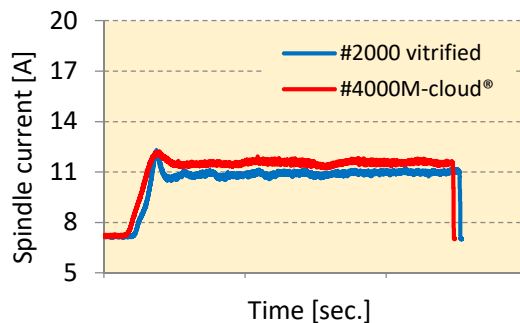
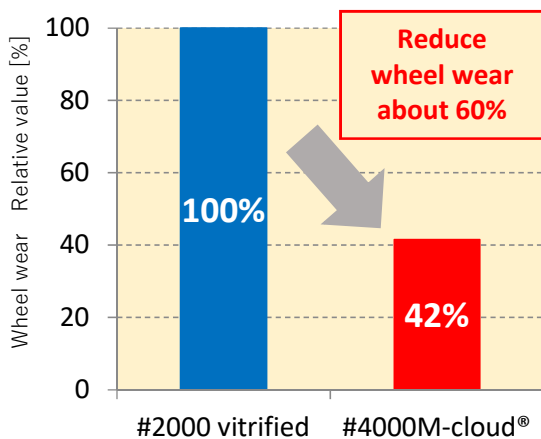
- ❖ Super-porous structure by unique manufacturing process.
- ❖ Adjustable porosity is available.

Grinding method	Infeed grinding
Workpiece	Semiconductor substrate Ex. SiC, GaN, Sapphire, Glass ,etc
Manufacturing range	Grain size : # 2000~ # 4000 Specification : Harder, Standard, Softer ※ Inquires on matters other than the above are also welcome .Please contact us.

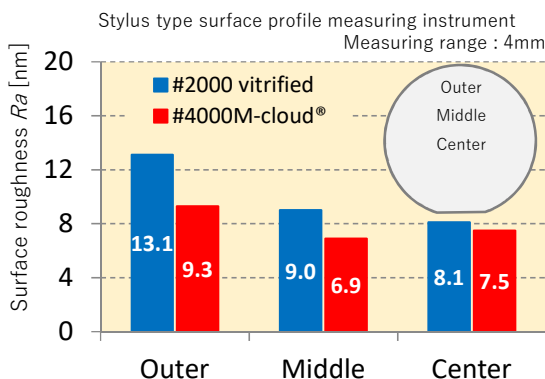
Establish compatibility between free cutting and wear resistance

#4000M-cloud® has excellent cutting ability. Wear resistance is less than half compared to #2000 vitrified bonded wheel

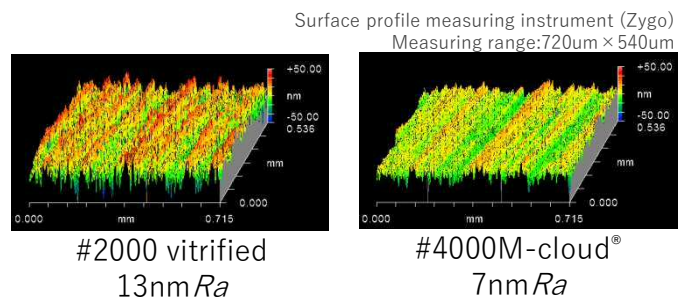
Wheel	#4000M-cloud®
Machine	Vertical type surface grinder
Wafer	Φ6inch SiC wafer (C plane)
Grinding condition	Spindle rotation : 1700min ⁻¹ Table rotation : 300min ⁻¹ Feed speed : 0.25um/sec.



Less grinding damage



Grinding amount at the post-process can be reduced by finer grain with free cutting ability



2021/3/22